



Henkel Solutions for Laminate Packaging Wafer Backside Coatings

ELECTRICALLY NON-CONDUCTIVE WAFER BACKSIDE COATINGS (WBC)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	MODULUS AT 25°C (MPa)	CTE (ppm/°C)		RECOMMENDED CURE
							Below T _g	Above T _g	
LOCTITE ABLESTIK WBC 8901UV	Die attach wafer backside coating adhesive	<ul style="list-style-type: none">• Wide process windows• 5 to 60 µm bondline control• Low viscosity before B-stage• Can be spray coated on Dicing Before Grinding (DBG) wafers• UV B-stage and oven cure	≤ 1 x 1	Solder mask, Cu, Ag or Au	L2 260°C capable	3,585	45	142	15 min. ramp and 30 min. hold at 90°C + 4 min. ramp and 45 min. hold at 120°C

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